SQJ481EP

AUTOMOTIVE

RoHS

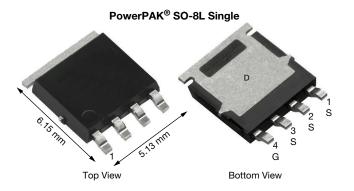
COMPLIANT HALOGEN

FREE

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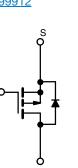
Automotive P-Channel 80 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	-80
$R_{DS(on)} (\Omega)$ at $V_{GS} = -10 V$	0.0800
$R_{DS(on)} (\Omega)$ at $V_{GS} = -4.5 V$	0.0950
I _D (A)	-16
Configuration	Single
Package	PowerPAK SO-8L

FEATURES

- TrenchFET[®] power MOSFET
- AEC-Q101 qualified
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unles	s otherwise noted	l)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-80	V
Gate-source voltage		V _{GS}	± 20	v
Continuous drain current	T _C = 25 °C	la la	-16	
	T _C = 125 °C	۱ _D	-9.2	
Continuous source current (diode conduction)		I _S	-41	A
Pulsed drain current ^a		I _{DM}	-60	
Single pulse avalanche current	L = 0.1 mH	I _{AS}	-24.5	
Single pulse avalanche energy	L = 0.1 mm	E _{AS}	30	mJ
Maximum power dissipation ^a	T _C = 25 °C	PD	45	w
	$T_{\rm C} = 125 ^{\circ}{\rm C}$		15	15
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) c, d			260	U U

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount ^b	R _{thJA}	70	°C/W	
Junction-to-case (drain)		R _{thJC}	3.3	0/10	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

b. When mounted on 1" square PCB (FR4 material)

d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

1

c. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8L. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



SPECIFICATIONS ($T_C = 25 \ ^{\circ}C$,		T\/D					
PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						1	1
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = -250 \ \mu A$		-80	-	-	v
Gate-Source Threshold Voltage	V _{GS(th)}		V _{GS} , I _D = -250 μA	-1.5	-2.0	-2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = -80 V	-	-	-1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V_{DS} = -80 V, T_{J} = 125 °C	-	-	-50	μA
		$V_{GS} = 0 V$	V_{DS} = -80 V, T _J = 175 °C	-	-	-150	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = -10 \text{ V}$	$V_{DS} = -5 V$	-10	-	-	Α
		$V_{GS} = -10 V$	I _D = -10 A	-	0.0651	0.0800	
Drain-Source On-State Resistance ^a	P	$V_{GS} = -10 V$	T _J = 125 °C	-	-	0.0140	Ω
Forward Transconductance ^b	R _{DS(on)}	$V_{GS} = -10 V$	T _J = 175 °C	-	-	0.0175	
		$V_{GS} = -4.5 V$	I _D = -7 A	-	0.0775	0.0950	
Forward Transconductance b	9 _{fs}	V _{DS} = -15 V, I _D = -10 A		-	20	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	1459	2000	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = -25 V, f = 1 MHz	-	148	200	pF
Reverse Transfer Capacitance	C _{rss}			-	95	130	
Total Gate Charge ^c	Qg			-	33	50	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = -10 V	$V_{DS} = -40 \text{ V}, I_D = -8 \text{ A}$	-	4.5	-	nC
Gate-Drain Charge ^c	Q _{gd}			-	7.5	-	
Gate Resistance	Rg		f = 1 MHz		2.1	3.2	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	12	20	
Rise Time ^c	tr	V _{DD} :	$V_{DD} = -40 \text{ V}, \text{ R}_{1} = 5 \Omega$		5	10	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -8$ Å, $V_{GEN} = -10$ V, $R_g = 1$ Ω		-	32	50	
Fall Time ^c	t _f	1		-	6	10	1
Source-Drain Diode Ratings and Chara	acteristics ^b	·					
Pulsed Current ^a	I _{SM}			-	-	-60	А
Forward Voltage	V _{SD}	le :	= -8 A, V _{GS} = 0	-	-0.84	-1.2	v

Notes

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 $\,\%$

b. Guaranteed by design, not subject to production testing

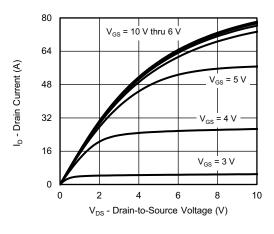
c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

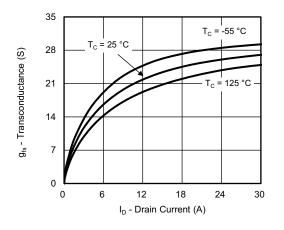
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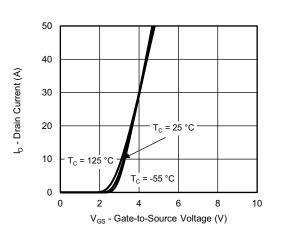
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



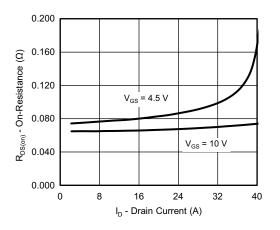
Output Characteristics



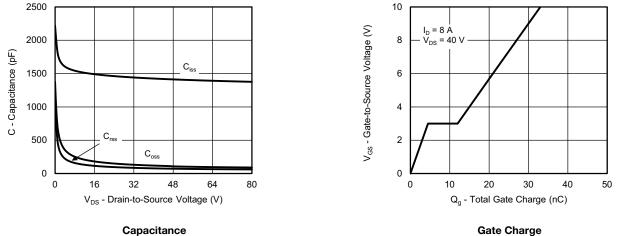
Transconductance



Transfer Characteristics



On-Resistance vs. Drain Current



Capacitance

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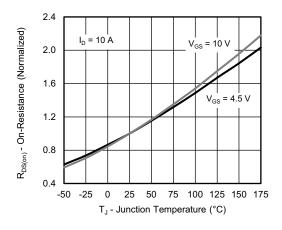
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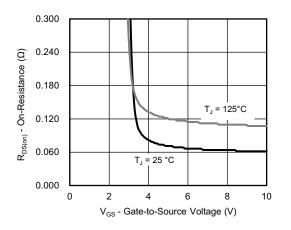
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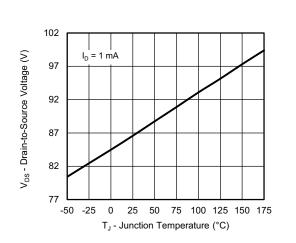
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

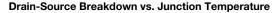


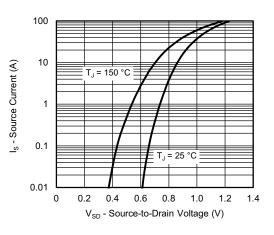
On-Resistance vs. Junction Temperature



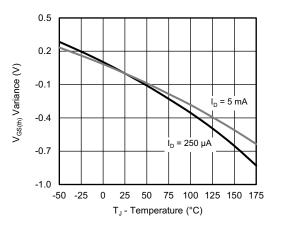
On-Resistance vs. Gate-to-Source Voltage



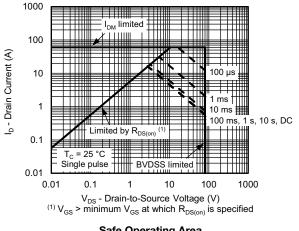




Source Drain Diode Forward Voltage



Threshold Voltage



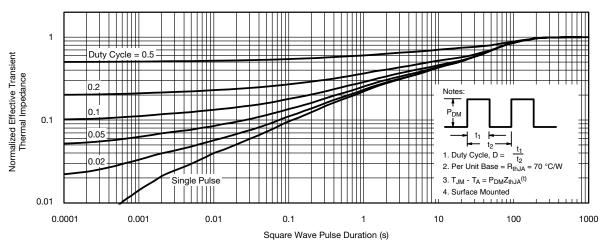
Safe Operating Area

4

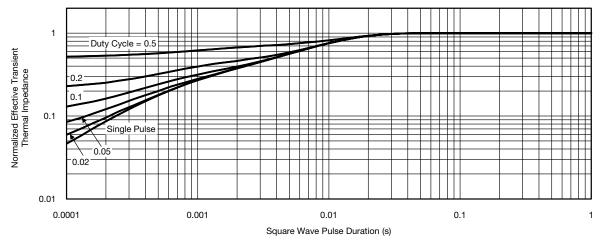
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THERMAL RATINGS (T_C = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

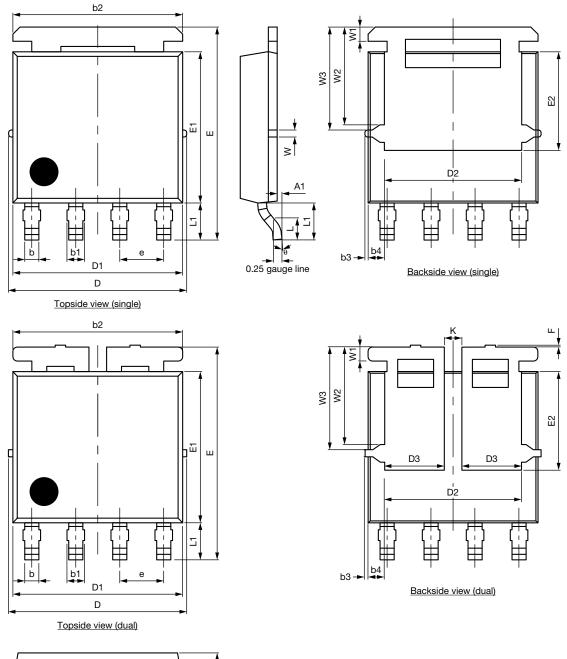
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

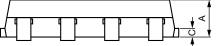
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Package Information



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DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
К		0.51			0.020		
W		0.23			0.009		
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

Note

• Millimeters will govern



RECOMMENDED MINIMUM PAD FOR PowerPAK[®] SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

Revision: 07-Feb-12



Vishay

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